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XP-002133479

AN - 1999-218980 [19]  
AP - JP19970208864 19970804  
CPY - SUMO  
DC - A89 E13 G06 L03 P84 U11  
FS - CPI;GMPI;EPI  
IC - G03F7/004 ; G03F7/039 ; H01L21/027  
MC - A04-C A08-M08 A12-E07C A12-L02B2 E07-D05 G06-D01 G06-D03 G06-F03C  
G06-F03D L04-C06B  
- U11-A06A U11-C04E U11-C04F U11-C04H  
M3 - [01] F011 F012 F014 F016 F017 F019 F433 F499 H102 H122 H181 H182 H201  
H202 H211 H212 J011 J012 J371 J372 M210 M211 M212 M213 M214 M215 M216  
M220 M221 M222 M223 M224 M225 M226 M231 M232 M233 M240 M262 M273 M281  
M282 M283 M312 M313 M315 M320 M321 M331 M332 M342 M383 M391 M413 M510  
M521 M522 M530 M540 M781 M903 M904 Q130 Q332 Q454 R043; 9919-DQL01-K  
9919-DQL01-U  
PA - (SUMO ) SUMITOMO CHEM CO LTD  
PN - JP11052575 A 19990226 DW199919 G03F7/039 008pp  
PR - JP19970208864 19970804  
XA - C1999-064486  
XIC - G03F-007/004 ; G03F-007/039 ; H01L-021/027  
XP - N1999-161818  
AB - J11052575 A chemically amplified positive photoresist composition  
comprises: (A) a resin which becomes increasingly alkali-soluble when  
treated with acid; (B) an acid generator; and (C) a piperidine-based  
hindered amine compound.  
- The hindered amine light stabiliser (C) preferably contains a moiety  
of formula (I).  
- R = H, optionally substituted alkyl or alkanoyl. The resin (A) may be  
a polyvinylphenol type resin in which the phenolic hydroxy groups are  
protected with acid-cleaving groups, or a resin containing at least  
one alicyclic ring and acid-cleaving group. The composition preferably  
contains 80-99.9 wt. % (A), 0.1-20 wt. % (B) and 0.0001-10 wt. % (C).  
- USE - The photoresist composition is useful for the lithographic  
production of semiconductor integrated circuits.  
- ADVANTAGE - The photoresist composition can be activated with  
high-energy radiation, e.g. far ultraviolet rays, electron rays or  
X-rays.  
- (Dwg.0/0)  
AW - LITHOGRAPHY SEMICONDUCTOR INTEGRATED CIRCUIT  
AKW - LITHOGRAPHY SEMICONDUCTOR INTEGRATED CIRCUIT  
CN - 9919-DQL01-K 9919-DQL01-U  
IW - CHEMICAL AMPLIFY POSITIVE PHOTORESIST COMPOSITION COMPRISE RESIN  
ALKALI SOLUBLE ACID TREAT ACID GENERATOR PIPERIDINE BASED HINDERED  
AMINE COMPOUND  
IKW - CHEMICAL AMPLIFY POSITIVE PHOTORESIST COMPOSITION COMPRISE RESIN  
ALKALI SOLUBLE ACID TREAT ACID GENERATOR PIPERIDINE BASED HINDERED  
AMINE COMPOUND  
NC - 001  
OPD - 1997-08-04  
ORD - 1999-02-26  
PAW - (SUMO ) SUMITOMO CHEM CO LTD

TI - Chemically amplified positive photoresist composition - comprises a resin which becomes alkali-soluble upon acid treatment, an acid generator and piperidine-based hindered amine compound

A01 - [001] 018 ; G0179 G0102 G0022 D01 D12 D10 D19 D18 D31 D51 D53 D58 D76 D88 F31 F30 D13-R ; H0000 ; H0011-R ; M9999 M2095-R ; L9999 L2391 ; L9999 L2095-R ; P1741 ;  
- [002] 018 ; ND01 ; K9790-R ; K9814 K9803 K9790 ; K9825 K9803 K9790 ; K9869 K9847 K9790 ; Q9999 Q8684 Q8673 Q8606 ; Q9999 Q7454 Q7330 ; Q9999 Q7476 Q7330 ; B9999 B5652 B3521 B3510 B3372 ;  
- [003] 018 ; D01 D11 D10 D23 D22 D31 D76 D41 F08 F07 ; A999 A771 ; A999 A204 ;